

## Description

RClamp arrays are ultra low capacitance ESD protection devices designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

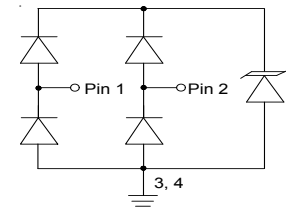
The RClamp0522P and RClamp0524P have a typical capacitance of only 0.30pF between I/O pins. This allows it to be used on circuits operating in excess of 3GHz without signal attenuation. They may be used to meet the ESD immunity requirements of IEC 61000-4-2. The RClamp0522P is designed to protect two lines, while the RClamp0524P will protect four lines. The RClamp0522P is in a 6-pin SLP1610P4 package. It measures 1.6 x 1.0 with a nominal height of 0.58mm. The RClamp0524PA is in a 10-pin SLP2510P8 package. It measures 2.5 x 1.0 with a nominal height of 0.58mm. The leads are spaced at a pitch of 0.5mm and are finished with lead-free NiPdAu. They are designed for easy PCB layout by allowing the traces to run straight through the device. The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications such as HDMI, DisplayPort™, MDDI, and eSATA interfaces.

## Features

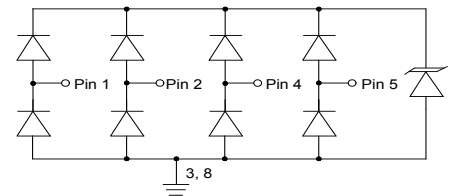
- ESD protection for high-speed data lines to
  - IEC 61000-4-2 (ESD) ±17kV (air), ±12kV (contact) IEC 61000-4-5 (Lightning) 5A (8/20µs)
  - IEC 61000-4-4 (EFT) 40A (5/50ns)
- Package design optimized for high speed lines
- Flow-Through design
- Protects two or four I/O lines
- Low capacitance: 0.3pF typical (I/O to I/O)
- Low clamping voltage
- Low operating voltage: 5V
- Solid-state silicon-avalanche technology

## Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P <sub>pk</sub>	150	W
Peak Pulse Current (tp = 8/20µs)	I <sub>pp</sub>	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	+/- 17 +/- 12	kV
Operating Temperature	T <sub>J</sub>	-55 to +125	°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C



2-Line Protection



4-Line Protection

## Applications

- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interface (DVI)
- DisplayPort™ Interface
- MDDI Ports
- PCI Express
- eSATA Interfaces

## Mechanical Characteristics

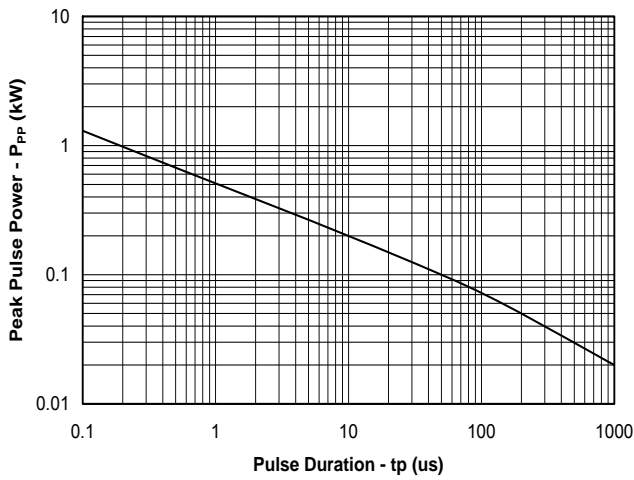
- SLP1610P4 6-pin package (1.6 x 1.0 x 0.58mm)
- SLP2510P8 10-pin package (2.5 x 1.0 x 0.58mm) Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Lead Pitch: 0.5mm
- Lead finish: NiPdAu

**Electrical Characteristics (T=25°C)**

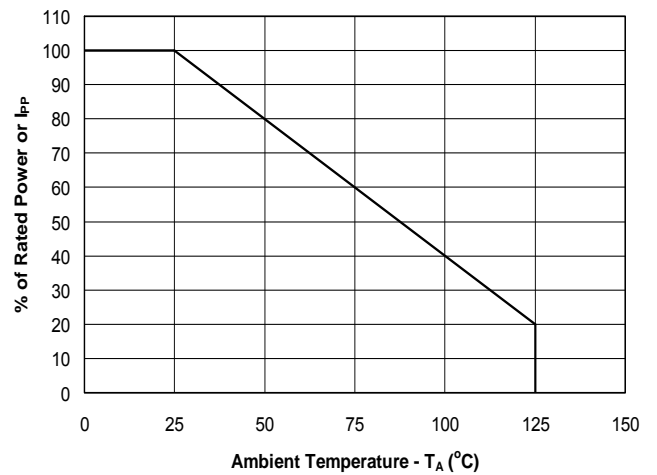
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$	Any I/O pin to ground			5	V
Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1\text{mA}$ Any I/O pin to ground	6			V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5\text{V}$ , T=25°C Any I/O pin to ground			1	μA
Clamping Voltage	$V_C$	$I_{pp} = 1\text{A}$ , $t_p = 8/20\mu\text{s}$ Any I/O pin to ground			15	V
Junction Capacitance	$C_j$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Between I/O pins		0.30	0.4	pF
Junction Capacitance	$C_j$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Any I/O pin to ground			0.8	pF

**Typical Characteristics**

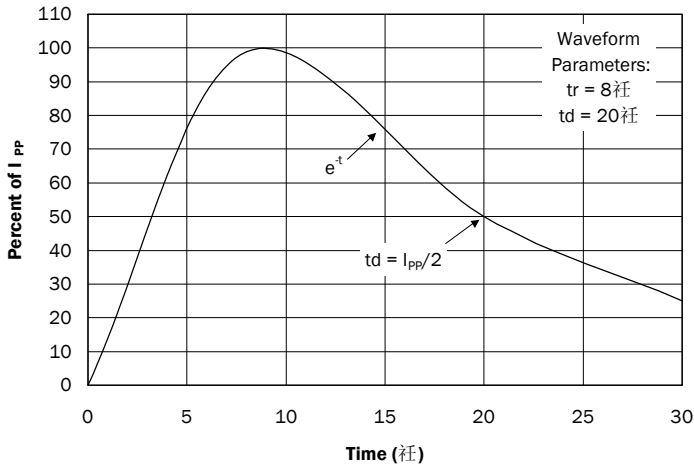
**Non-Repetitive Peak Pulse Power vs. Pulse Time**



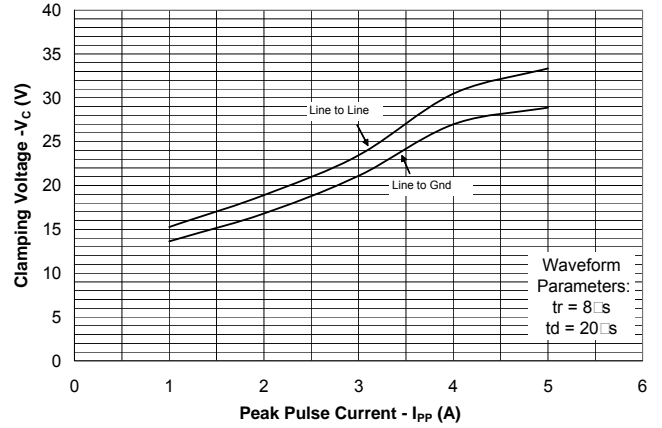
**Power Derating Curve**



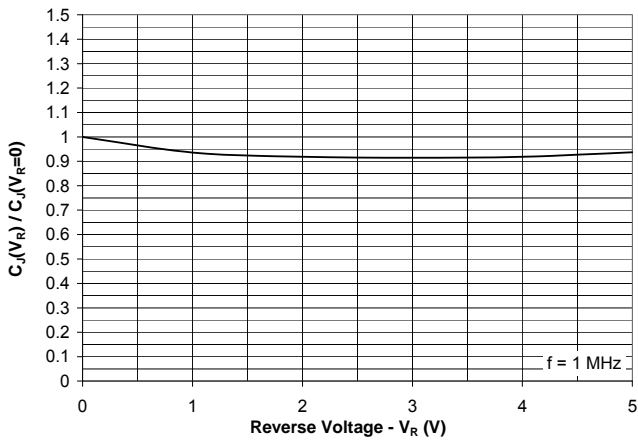
**Pulse Waveform**



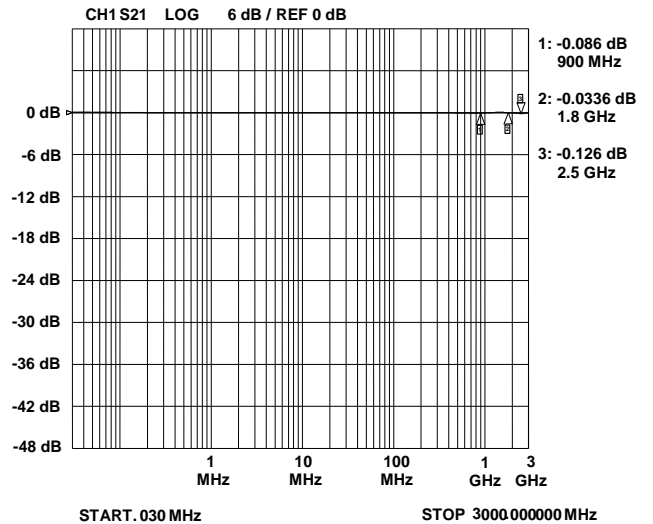
**Clamping Voltage vs. Peak Pulse Current (Between any I/O and Ground)**



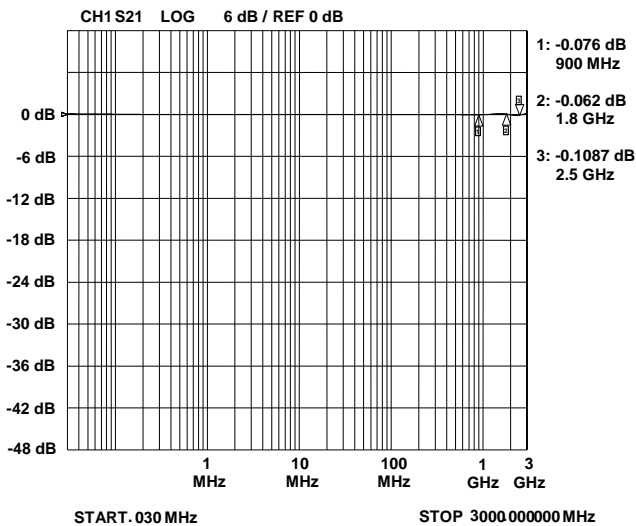
**Normalized Capacitance vs. Reverse Voltage**



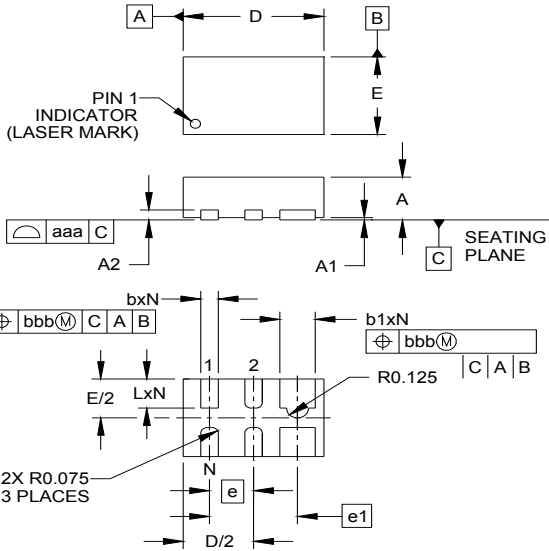
**Insertion Loss S21 - I/O to GND**



**Insertion Loss S21 - I/O to I/O**



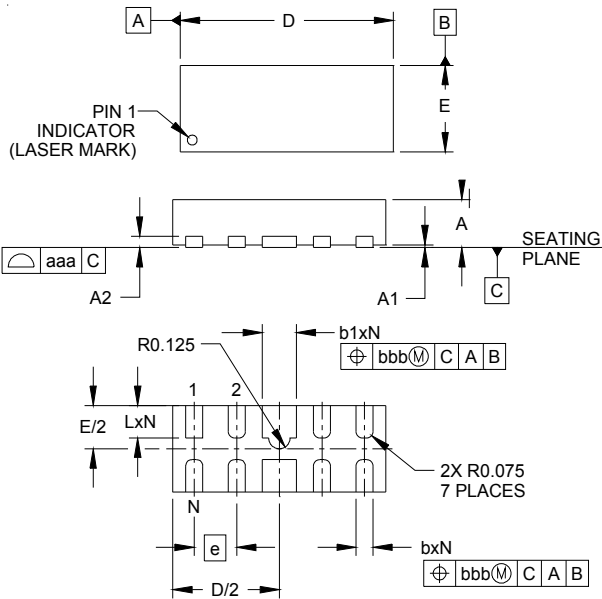
Outline Drawing - SLP1610P4/SLP2510P8



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2	(.005)			(0.13)		
b	.006	.008	.010	0.15	0.20	0.25
b1	.014	.016	.018	0.35	0.40	0.45
D	.059	.063	.067	1.50	1.60	1.70
E	.035	.039	.043	0.90	1.00	1.10
e	.020 BSC		0.50 BSC			
e1	.039 BSC		1.00 BSC			
L	.012	.015	.017	0.30	0.38	0.43
N	4			4		
aaa	.003			0.08		
bbb	.004			0.10		

NOTES:  
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

SLP1610P4

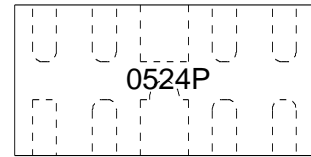
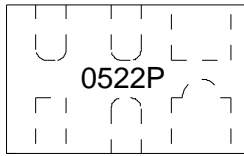


DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2	(.005)			(0.13)		
b	.006	.008	.010	0.15	0.20	0.25
b1	.014	.016	.018	0.35	0.40	0.45
D	.094	.098	.102	2.40	2.50	2.60
E	.035	.039	.043	0.90	1.00	1.10
e	.020 BSC		0.50 BSC			
L	.012	.015	.017	0.30	0.38	0.425
N	8			8		
aaa	.003			0.08		
bbb	.004			0.10		

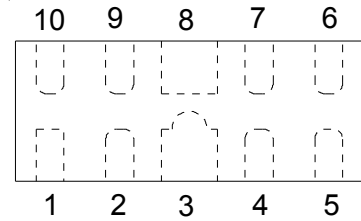
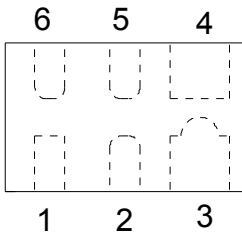
NOTES:  
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SLP2510P8

**Marking**



**Pin Identification and Configuration**

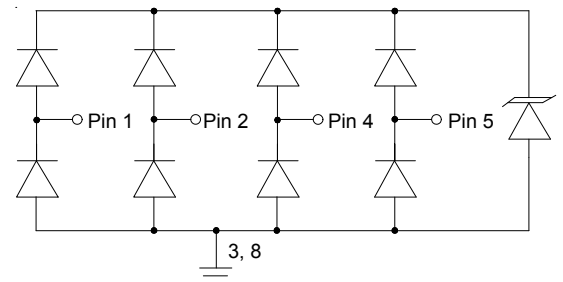
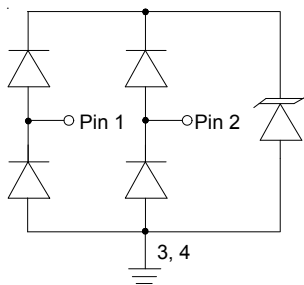


Pin	Identification
1 - 2	Input Lines
5 - 6	Output Lines (No Internal Connection)
3 - 4	Ground

Pin	Identification
1, 2, 4, 5	Input Lines
6, 7, 9, 10	Output Lines (No Internal Connection)
3, 8	Ground

**SLP1610P4 Pin Configuration (Top View)**

**SLP2510P8 Pin Configuration (Top View)**



**Circuit Diagram**

**Circuit Diagram**

**Ordering information**

Order code	Package	Base qty	Delivery mode
UMW RCLAMP0522P.TCT	SLP1610P4	3000	Tape and reel
UMW RCLAMP0524P	SLP2510P8	3000	Tape and reel

单击下面可查看定价，库存，交付和生命周期等信息

[>>UMW\(友台半导体\)](#)